



Material Content Data Sheet



Sales Product Name		TLE9844-2QX		Issued		25. January 2018		
MA#		MA001472566						
Package		PG-VQFN-48-31		Weight*		129.64 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.417	2.64	2.64	26360	26360
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138	
	non noble metal	zinc	7440-66-6	0.072	0.06		553	
	non noble metal	iron	7439-89-6	1.433	1.11		11055	
wire	non noble metal	copper	7440-50-8	58.193	44.89	46.07	448880	460626
	non noble metal	copper	7440-50-8	0.599	0.46	0.46	4622	4622
	encapsulation	organic material	carbon black	1333-86-4	0.185	0.14		1429
plastics	plastics	epoxy resin	-	7.840	6.05		60477	
	inorganic material	silicondioxide	60676-86-0	53.708	41.43	47.62	414288	476194
leadfinish	non noble metal	tin	7440-31-5	2.596	2.00	2.00	20028	20028
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4735	4735
glue	plastics	epoxy resin	-	0.222	0.17		1710	
	noble metal	silver	7440-22-4	0.742	0.57	0.74	5725	7435
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com